

**IGBT Modules** 

### Power Module (V series) 1700V / 450A / 2-in-1 package

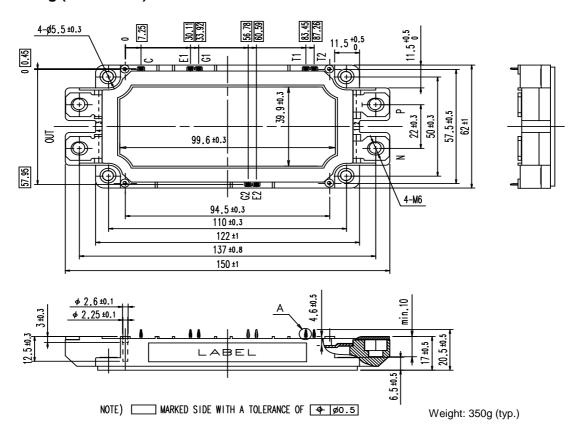
#### **■** Features

Low V<sub>CE(sat)</sub> Low Inductance Module structure Solderless press-fit terminals

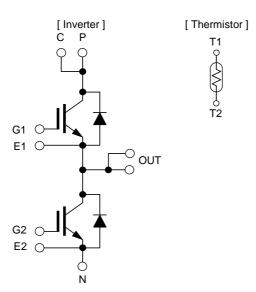
#### ■ Applications

Inverter for Motor Drives, AC and DC Servo Drives
Uninterruptible Power Supply Systems, Wind Turbines, PV Power Conditioning Systems

### ■ Outline drawing (Unit:mm)



#### **■** Equivalent Circuit



**IGBT Modules** 

### ■ Absolute Maximum Ratings (at T<sub>C</sub>= 25°C unless otherwise specified)

Items		Symbols	Conditions		Maximum Ratings	Units
Collector-Emitter voltage		V <sub>CES</sub>			1700	V
Gate-Emit	Gate-Emitter voltage				±20	V
	Collector current		Continuous	T <sub>C</sub> =25°C	600	
				T <sub>C</sub> =100°C	450	
Collector			1ms		900	A
					450	
		-I <sub>C</sub> pulse	1ms		900	
Collector	Collector power dissipation		1 device		2500	W
Junction temperature		T <sub>j</sub>			175	
Operating junction temperature		T <sub>jop</sub>			450	1
(under switching conditions)					150	°C
Case temperature		T <sub>c</sub>			125	
Storage temperature		T <sub>stg</sub>			-40 ~ 125	
Isolation	between terminal and copper base (*1)	V	AC: 1min.		3400	VAC
voltage	between thermistor and others (*2)	$V_{iso}$	AC. IIIIII.		3400	VAC
Screw	Mounting (*3)	-			3.5	N m
Torque	rque Terminals (*4)				4.5	INIII

<sup>(\*1)</sup> All terminals should be connected together during the test.

(\*3) Recommendable Value: 2.5-3.5 Nm (M5) (\*4) Recommendable Value: 3.5-4.5 Nm (M6)

<sup>(\*2)</sup> Two thermistor terminals should be connected together, other terminals should be connected together and shorted to base plate during the test.

**IGBT Modules** 

### ■ Electrical characteristics (at T<sub>j</sub>= 25°C unless otherwise specified)

Items	Symbole	ymbols Conditions			Characteristics			
items	Symbols	Conditions		min.	typ.	max.	Units	
Zero gate voltage Collector current	I <sub>CES</sub> V <sub>GE</sub> =0V, V <sub>CE</sub> =1700V		1700V	-	-	3.0	mA	
Gate-Emitter leakage current	I <sub>GES</sub>	V <sub>CE</sub> =0V, V <sub>GE</sub> =±20V		-	-	600	nA	
Gate-Emitter threshold voltage	$V_{\text{GE(th)}}$	V <sub>CE</sub> =20V, I <sub>C</sub> =450mA		6.0	6.5	7.0	V	
	V <sub>CE(sat)</sub> (terminal)		T <sub>j</sub> =25°C	-	2.65	3.10	V	
			T <sub>j</sub> =125°C	-	3.10	-		
Collector-Emitter		$V_{GE} = 15V$ $I_{C} = 450A$	T <sub>j</sub> =150°C	-	3.15	-		
saturation voltage	V <sub>CE(sat)</sub> (chip)		T <sub>j</sub> =25°C	-	2.00	2.45		
			T <sub>j</sub> =125°C	-	2.45	-		
			T <sub>j</sub> =150°C	-	2.50	-		
Internal gate resistance	R <sub>G(int)</sub>	-		-	1.67	-	Ω	
Input capacitance	C <sub>ies</sub>	V <sub>CE</sub> =10V, V <sub>GE</sub> =0V, f=1MHz		-	40	-	nF	
	t <sub>on</sub>			-	900	-		
Turn-on time	t <sub>r</sub>	$V_{CC}$ = 900V $V_{GE}$ = ±15V		-	-	400	-	
	$t_{r(i)}$		$R_G = 3.3\Omega$	-	100	-	nsec	
Turn-off time	t <sub>off</sub>	L <sub>s</sub> = 80nH		-	1300	-		
Tarri on time	$t_f$	1		-	100	-		
	V <sub>F</sub> (terminal)		T <sub>j</sub> =25°C	-	2.45	2.90	V	
			T <sub>j</sub> =125°C	-	2.75	-		
Converd on voltage		$V_{GE} = 0V$ $I_{F} = 450A$	T <sub>j</sub> =150°C	-	2.70	-		
Forward on voltage	V <sub>F</sub> (chip)		T <sub>j</sub> =25°C	-	1.80	2.25		
			T <sub>j</sub> =125°C	-	2.10	-		
			T <sub>i</sub> =150°C	-	2.05	-		
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 450A		-	250	-	nsec	
Thermistor Resistance		T=25°C		-	5000	-	Ω	
		T=100°C		465	495	520		
Thermistor B value	В	T=25/50°C		3305	3375	3450	K	

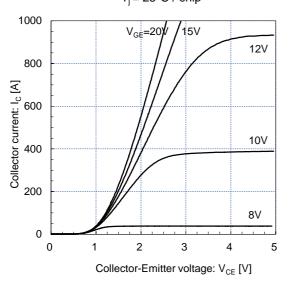
#### 5. Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
ILEIIIS	Syllibols	Conditions	min.	typ.	max.	Ullits
Thermal resistance	D	IGBT	-	-	0.06	°C/W
(1device)	$R_{th(j-c)}$	FWD	-	-	0.10	
Contact thermal resistance (1device) (*1)	R <sub>th(c-f)</sub>	with thermal compound	-	0.0167	-	C/VV

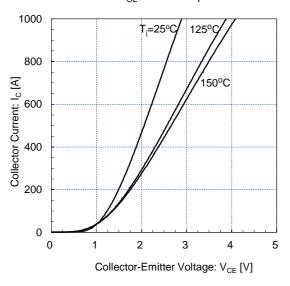
<sup>(\*1)</sup> This is the value which is defined mounting on the additional cooling fin with thermal compound.

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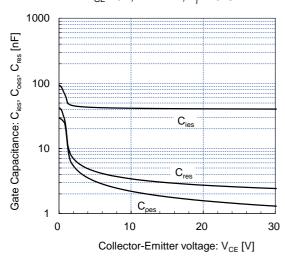
Collector current vs. Collector-Emitter voltage  $T_i = 25^{\circ}C$  / chip



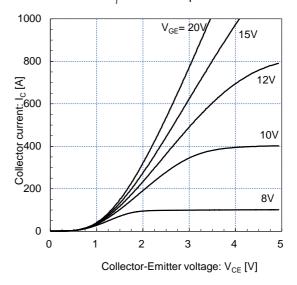
Collector current vs. Collector-Emitter voltage  $V_{GE} = 15V / chip$ 



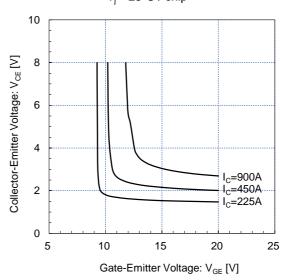
Capacitance vs. Collector-Emitter Voltage  $V_{GE}$ = 0V, f= 1MHz,  $T_i$ = 25°C



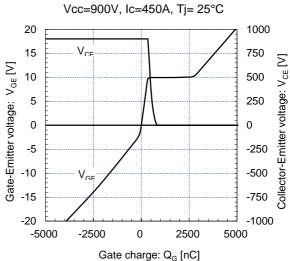
Collector current vs. Collector-Emitter voltage (typ.)  $T_i = 150^{\circ}C$  / chip



Collector-Emitter voltage vs. Gate-Emitter voltage  $T_i = 25^{\circ}\text{C}$  / chip

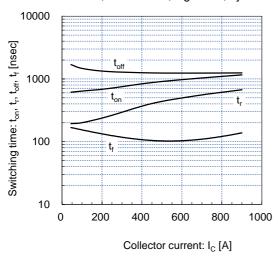


Dynamic Gate Charge (typ.)

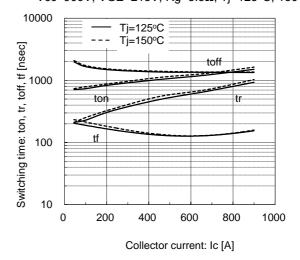


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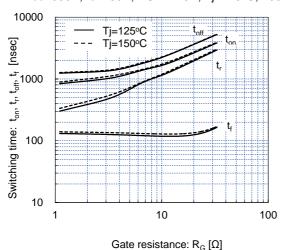
Switching time vs. Collector current (typ.) Vcc=900V, VGE= $\pm$ 15V, Rg= $3.3\Omega$ , Tj= $25^{\circ}$ C



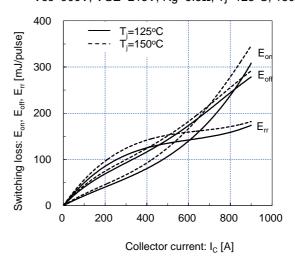
Switching time vs. Collector current (typ.) Vcc=900V, VGE=±15V, Rg=3.3Ω, Tj=125°C, 150°C



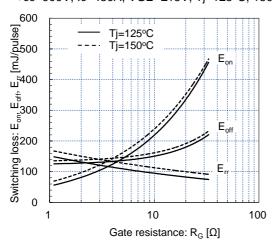
Switching time vs. Gate resistance (typ.) /cc=900V, Ic=450A, VGE=±15V, Tj=125°C, 150°C



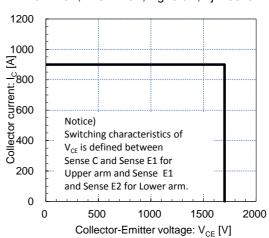
Switching loss vs. Collector current (typ.) Vcc=900V, VGE=±15V, Rg=3.3Ω, Tj=125°C, 150°C



Switching loss vs. Gate resistance (typ.) /cc=900V, Ic=450A, VGE=±15V, Tj=125°C, 150°C



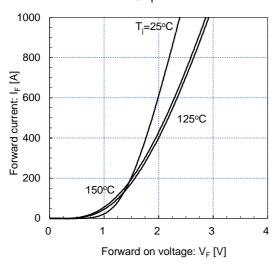
Reverse bias safe operating area (max.) +VGE=15V, -VGE=15V, Rg= $3.3\Omega$ , Tj= $150^{\circ}$ C



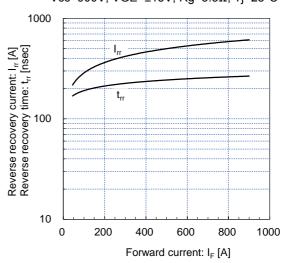


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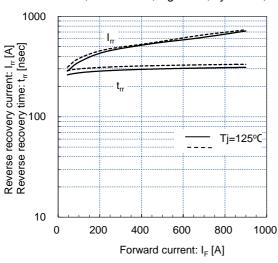
Forward current vs. Forward vltage (typ.) chip



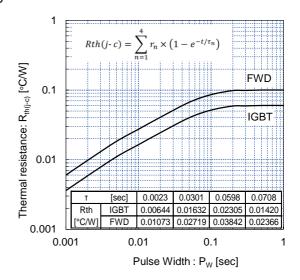
Reverse recovery characteristics (typ.) Vcc=900V, VGE=±15V, Rg=3.3Ω, Tj=25°C



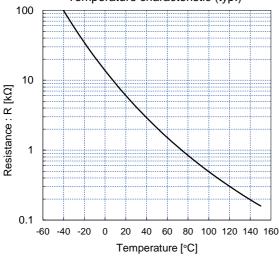
Reverse Recovery Characteristics (typ.) Vcc=900V, VGE=±15V, Rg=3.3Ω, Tj=125°C,150°C

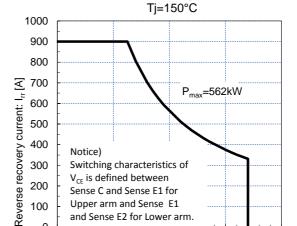


Transient Thermal Resistance (max.)



[THERMISTOR] Temperature characteristic (typ.) 100





and Sense E2 for Lower arm.

100

6

0

FWD safe operating area (max.)

Collector-Emitter voltage: V<sub>CE</sub> [V] FM5F8405 2014/11

2000

1500

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